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(54) **Multichip module packaging process for known good die burn-in**

Verpackungs-Verfahren für Vielchip-Modul mit Einbrenn-Test zur Erhaltung von als gut erkannten Chips ("Known Good Die")

Procédé d'emballage d'un module multipuce avec déverminage en vue de l'obtention de puces reconnues bonnes ("known good die")

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